L Number	Hits	Search Text	DB	Time stamp
1	13095	<pre>(chip or die) and ((pad or land) with   (solder or ball or balls))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/03/07 21:30
2	4231	(chip or die) and ((pad or land) with (balls or bumps))	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/03/07 22:04
3	2844	((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/03/07 23:10
4	86	(((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/777.ccls.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/03/07 20:59
5	263	(((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/778.ccls.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/07 21:26
6	229	((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/778.ccls.) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/777.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 21:32
7	3	6291897.URPN.	USPAT	2004/03/07
8	29	("Re27934"   "3202888"   "4263606"   "4390771"   "4597519"   "4804132"   "5207585"   "5214308"   "5329423"   "5373111"   "5426266"   "5428298"   "5457344"   "5508561"   "5532613"   "5545589"   "5545920"   "5550083"   "5559054"   "5559366"   "5585282"   "5592736"   "5656858"   "5726501"   "5726502"   "5736790"   "5783865"   "5783870"   "5801449").PN.	USPAT	2004/03/07 21:12
9	9	("2934685"   "3809625"   "3871014"   "4369458"   "4600600"   "4838347"   "5001542"   "5010038"   "5207585").PN.	USPAT	2004/03/07 21:21
10	1	5955784.URPN.	USPAT	2004/03/07 21:22
11	166	(((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/780.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/07 21:24
12	115	<pre>((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad&lt;20010212)) and 257/780.ccls.) not ((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad&lt;20010212)) and 257/778.ccls.) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad&lt;20010212)) and 257/777.ccls.))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 21:26
13	96	(((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/779.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/07 21:26

				1
14	55	((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212))	USPAT; US-PGPUB;	2004/03/07 21:26
		and 257/779.ccls.) not (((chip or die)	EPO; JPO;	21.20
		and ((pad or land) with (balls or	DERWENT;	
		bumps))) and (@ad<20010212)) and   257/780.ccls.)	IBM_TDB	
15	3		USPAT	2004/03/07 21:27
16	4	("3871015"   "5266520"   "6020561"   "6066551").PN.	USPAT	2004/03/07
17	4231	(chip or die) and ((pad or land) with (balls or bumps))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/07 21:32
18	2844	((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/07 21:31
19	2362	(((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and (semiconductor or ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/07 21:31
20	1770	<pre>((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad&lt;20010212)) and (semiconductor or ic)) and (solder with (balls or bumps))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/07 21:32
21	1699	<pre>(((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad&lt;20010212)) and (semiconductor or ic)) and (solder with (balls or bumps))) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad&lt;20010212)) and 257/777.ccls.)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 21:58
22	1508		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 21:33
23	1486	(((((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and (semiconductor or ic)) and (solder with (balls or bumps))) not ((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/777.ccls.)) not ((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/778.ccls.) not ((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/777.ccls.))) not ((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/779.ccls.)) not ((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and (pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/780.ccls.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 23:12

			<del> </del>	
24	946	((((((chip or die) and ((pad or land)	USPAT;	2004/03/07
		with (balls or bumps))) and	US-PGPUB;	23:11
		(@ad<20010212)) and (semiconductor or	EPO; JPO;	
	İ	ic)) and (solder with (balls or bumps)))	DERWENT;	
		not ((((chip or die) and ((pad or land)	IBM_TDB	
		with (balls or bumps))) and	_	
		(@ad<20010212)) and 257/777.ccls.)) not		
		((((chip or die) and ((pad or land) with		
		(balls or bumps))) and (@ad<20010212))		
}		and 257/778.ccls.) not (((chip or die)		
		and ((pad or land) with (balls or		
		bumps))) and (@ad<20010212)) and		
		257/777.ccls.))) not ((((chip or die)		
		and ((pad or land) with (balls or		
		bumps))) and (@ad<20010212)) and		
		257/779.ccls.) not (((chip or die) and		
		((pad or land) with (balls or bumps)))		
		and (@ad<20010212)) and 257/780.ccls.)))		
		and 257/\$.ccls.		
25	447	(((((((chip or die) and ((pad or land)	USPAT;	2004/03/07
1		with (balls or bumps))) and	US-PGPUB;	21:57
		(@ad<20010212)) and (semiconductor or	EPO; JPO;	
		ic)) and (solder with (balls or bumps)))	DERWENT;	
		not ((((chip or die) and ((pad or land)	IBM TDB	
		with (balls or bumps))) and	_	
		(@ad<20010212)) and 257/777.ccls.)) not		
		((((chip or die) and ((pad or land) with		
		(balls or bumps))) and (@ad<20010212))		
		and 257/778.ccls.) not (((chip or die)		
		and ((pad or land) with (balls or		
		bumps))) and (@ad<20010212)) and		
		257/777.ccls.))) not ((((chip or die)		
		and ((pad or land) with (balls or		
		bumps))) and (@ad<20010212)) and		
		257/779.ccls.) not ((((chip or die) and		
		((pad or land) with (balls or bumps)))		
1		and (@ad<20010212)) and 257/780.ccls.)))		
1		and 438/\$.ccls.		

	T		1105-0	2004/02/25
26	66	<pre>(((((((((chip or die) and ((pad or land) with (balls or bumps))) and   (@ad&lt;20010212)) and (semiconductor or ic)) and (solder with (balls or bumps))) not ((((chip or die) and ((pad or land) with (balls or bumps))) and   (@ad&lt;20010212)) and 257/777.ccls.)) not   ((((chip or die) and ((pad or land) with   (balls or bumps))) and (@ad&lt;20010212)) and 257/778.ccls.) not ((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad&lt;20010212)) and 257/777.ccls.))) not ((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad&lt;20010212)) and 257/779.ccls.) not ((((chip or die) and   ((pad or land) with (balls or bumps))) and (@ad&lt;20010212)) and 257/780.ccls.))) and 438/\$.ccls.) not ((((((((chip or die) and   ((pad or land) with (balls or bumps))) and (@ad&lt;20010212)) and (solder with   (balls or bumps))) not ((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad&lt;20010212)) and 257/777.ccls.)) not (((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad&lt;20010212)) and 257/777.ccls.)) not ((((chip or die) and   ((pad or land) with (balls or bumps))) and (@ad&lt;20010212)) and 257/778.ccls.) not ((((chip or die) and ((pad or land) with (balls or bumps))) and   (@ad&lt;20010212)) and 257/777.ccls.))) not   ((((chip or die) and ((pad or land) with (balls or bumps))) and   (@ad&lt;20010212)) and 257/777.ccls.))) not   ((((chip or die) and ((pad or land) with   (balls or bumps))) and   (@ad&lt;20010212)) and 257/777.ccls.))) not   ((((chip or die) and ((pad or land) with   (balls or bumps))) and   (@ad&lt;20010212)) and   257/779.ccls.) not ((((chip or die) and   (257/779.ccls.) not ((((chip or die) and   (257/779.</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 21:58
27	1	and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/780.ccls.)) and 257/\$.ccls.) ("5955784").PN.	USPAT	2004/03/07
28	128	((chip or die) and ((pad or land) with (balls or bumps))) and ((pad or land) with (round or rounded or circle or semicircle))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	22:03 2004/03/07 22:05
30	749	((chip or die) and ((pad or land) with (balls or bumps))) and ((pad or land) with (x or v or l or shape or round or rounded or circle or semicircle))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/07 22:08
29	74	(((chip or die) and ((pad or land) with (balls or bumps))) and ((pad or land) with (round or rounded or circle or semicircle))) and (@ad<20010212)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/07 22:05
31	189	((chip or die) and ((pad or land) with (balls or bumps))) and ((pad or land) with (x or v or l))	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/03/07 22:08
32	124	(((chip or die) and ((pad or land) with (balls or bumps))) and ((pad or land) with (x or v or l))) and (@ad<20010212)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/07 22:57
33	1	("5578527").PN.	USPAT	2004/03/07
34	3574	((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20020212)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	22:57 2004/03/07 23:26

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35	2060	(((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20020212)) and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/07
36	1114	((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20020212)) and 257/\$.ccls.) not (((((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and (semiconductor or ic)) and (solder with (balls or bumps))) not ((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/777.ccls.)) not ((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/778.ccls.) not ((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/777.ccls.))) not ((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/777.ccls.)) not ((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/779.ccls.) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/780.ccls.))) and 257/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 23:13
37	868	(((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20020212)) and 438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/07 23:26
38	868	((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20020212)) and 438/\$.ccls.) and (@ad<20020212)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/07 23:26
39	536	<pre>(((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad&lt;20020212)) and 438/\$.ccls.) and (@ad&lt;20020212)) not (((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad&lt;20020212)) and 257/\$.ccls.) not (((((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad&lt;20010212)) and (semiconductor or ic)) and (solder with (balls or bumps))) not ((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad&lt;20010212)) and 257/777.ccls.)) not ((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad&lt;20010212)) and 257/778.ccls.) not ((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad&lt;20010212)) and 257/777.ccls.))) not ((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad&lt;20010212)) and 257/777.ccls.))) not ((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad&lt;20010212)) and 257/779.ccls.) not ((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad&lt;20010212)) and 257/780.ccls.))) and 257/\$.ccls.))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 23:27